

AMENDMENTS TO THE CLAIMS

1. (Withdrawn) A wafer storage method for preventing bonding pad fluoridation, comprising:

providing a shipping box for a wafer, the shipping box having at least one through hole;

providing a packaging bag to contain the shipping box;

pumping air from the packaging bag and the shipping box;

introducing a dry inert gas into the packaging bag and the shipping box until approaching atmospheric pressure; and

sealing the packaging bag.

2. (Withdrawn) The wafer storage method as claimed in claim 1, wherein air inside the packaging bag and the shipping box is pumped out by a vacuum packaging machine until pressure is dropped to 350-400 mmHg.

3. (Withdrawn) The wafer storage method as claimed in claim 1, wherein the dry inert gas is nitrogen.

4. (Original) A wafer-shipping device, comprising:

a shipping box for a wafer, the shipping box having at least one through hole;

a packaging bag to contain the shipping box; and

a dry inert gas filling the packaging bag and the shipping box, surrounding the wafer.

5. (Currently Amended) The wafer-shipping device as claimed in claim 4, wherein the pressure inside the shipping box is ~~approaching~~approximates atmospheric pressure.

6. (Original) The wafer-shipping device as claimed in claim 4, wherein the dry inert gas is nitrogen.

7. (New) The wafer-shipping device as claimed in claim 4, wherein after pumping an air out of the shipping box and the packaging bag, the dry inert gas fills the shipping box and the packaging bag.

8. (New) A wafer preserver, comprising:
a container having at least a vacant space;
a wrapping for packaging the container; and
a gas filling the container and surrounding the wafer.

9. (New) The wafer preserver as claimed in claim 8, wherein the pressure inside the container approximates atmospheric pressure.

10. (New) The wafer preserver as claimed in claim 8, wherein the gas is dry nitrogen.

11. (New) The wafer preserver as claimed in claim 8, wherein after pumping an air from the container and the wrapping, the gas fills the container and the wrapping.

12. (New) A semiconductor preserver, comprising:

a first space for containing the semiconductor;

a second space is formed by a gas-proof material surrounding the first space;

a vacant space between the first space and second space; and

an insert gas filling the first space, the second space and the vacant space.

13. (New) The semiconductor preserver as claimed in claim 12, wherein the pressure inside the first space approximates atmospheric pressure.

14. (New) The semiconductor preserver as claimed in claim 12, wherein the insert gas is dry nitrogen.

15. (New) The semiconductor preserver as claimed in claim 12, wherein after pumping an air out of the first space, the second space and vacant space, the inert gas fills the first space, the second space and vacant space.